

# PC8171xNSZ Series

## Low Input Current Type Photocoupler

### ■ Features

1. Low input current type ( $I_F=0.5\text{mA}$ )
2. High resistance to noise due to high common rejection voltage (CMR:MIN.  $10\text{kV}/\mu\text{s}$ )
3. Compact dual-in line package
4. Isolation voltage ( $V_{\text{iso}}$ ):  $5\text{kV}_{\text{rms}}$
5. Recognized by UL, file No. E64380

### ■ Applications

1. Programmable controllers
2. Facsimiles
3. Telephones

### ■ Rank Table

| Model No.  | Rank mark          | $I_c$ (mA) | Conditions   |
|------------|--------------------|------------|--|
| PC81710NSZ | A, B, C or no mark | 0.5 to 3.0 | $I_F=0.5\text{mA}$<br>$V_{CE}=5\text{V}$<br>$T_a=25^\circ\text{C}$ |
| PC81711NSZ | A                  | 0.6 to 1.5 |  |
| PC81712NSZ | B                  | 0.8 to 2.0 |  |
| PC81713NSZ | C                  | 1.0 to 2.5 |  |
| PC81715NSZ | A or B             | 0.6 to 2.0 |  |
| PC81716NSZ | B or C             | 0.8 to 2.5 |  |
| PC81718NSZ | A, B or C          | 0.6 to 2.5 |  |

### ■ Absolute Maximum Ratings ( $T_a=25^\circ\text{C}$ )

|        | Parameter                   | Symbol           | Rating      | Unit                     |
|--------|-----------------------------|------------------|-------------|--------------------------|
| Input  | Forward current             | $I_F$            | 10          | mA                       |
|        | *1 Peak forward current     | $I_{FM}$         | 200         | mA                       |
|        | Reverse voltage             | $V_R$            | 6           | V                        |
|        | Power dissipation           | $P$              | 15          | mW                       |
| Output | Collector-emitter voltage   | $V_{CEO}$        | 70          | V                        |
|        | Emitter-collector voltage   | $V_{ECO}$        | 6           | V                        |
|        | Collector current           | $I_c$            | 50          | mA                       |
|        | Collector power dissipation | $P_c$            | 150         | mW                       |
|        | Total power dissipation     | $P_{tot}$        | 170         | mW                       |
|        | Operating temperature       | $T_{opr}$        | -30 to +100 | $^\circ\text{C}$         |
|        | Storage temperature         | $T_{stg}$        | -55 to +125 | $^\circ\text{C}$         |
|        | *2 Isolation voltage        | $V_{\text{iso}}$ | 5           | $\text{kV}_{\text{rms}}$ |
|        | *3 Soldering temperature    | $T_{sol}$        | 260         | $^\circ\text{C}$         |

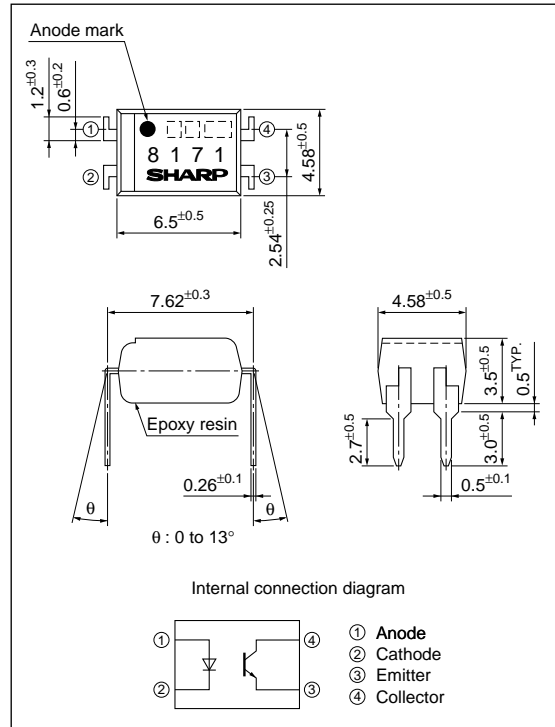
\*1 Pulse width  $\leq 100\mu\text{s}$ , Duty ratio = 0.001

\*2 40 to 60%RH, AC for 1 minute,  $f=60\text{Hz}$

\*3 For 10s

### ■ Outline Dimensions

(Unit : mm)



■ Electro-optical Characteristics

(Ta=25°C)

| Parameter                        |                                      | Symbol        | Conditions   | MIN.  | TYP.               | MAX. | Unit              |               |
|----------------------------------|--------------------------------------|---------------|--|---|--------------------|------|-------------------|---------------|
| Input                            | Forward voltage                      | $V_F$         | $I_F=10\text{mA}$  | —   | 1.2                | 1.4  | V                 |               |
|                                  | Reverse current                      | $I_R$         | $V_R=4\text{V}$  | —   | —                  | 10   | $\mu\text{A}$     |               |
|                                  | Terminal capacitance                 | $C_t$         | $V=0, f=1\text{kHz}$   | —   | 30                 | 250  | pF                |               |
| Output                           | Collector dark current               | $I_{CEO}$     | $V_{CE}=50\text{V}, I_F=0$   | —   | —                  | 100  | nA                |               |
|                                  | Collector-emitter breakdown voltage  | $BV_{CEO}$    | $I_C=0.1\text{mA}, I_F=0$  | 70  | —                  | —    | V                 |               |
|                                  | Emitter-collector breakdown voltage  | $BV_{ECO}$    | $I_E=10\mu\text{A}, I_F=0$   | 6   | —                  | —    | V                 |               |
| Transfer characteristics         | Collector current                    | $I_C$         | $I_F=0.5\text{mA}, V_{CE}=5\text{V}$   | 0.5   | —                  | 3.0  | mA                |               |
|                                  | Collector-emitter saturation voltage | $V_{CE(sat)}$ | $I_F=10\text{mA}, I_C=1\text{mA}$  | —   | —                  | 0.2  | V                 |               |
|                                  | Isolation resistance                 | $R_{ISO}$     | DC500V 40 to 60%RH   | $5 \times 10^{10}$                                | $1 \times 10^{11}$ | —    | $\Omega$          |               |
|                                  | Floating capacitance                 | $C_f$         | $V=0, f=1\text{MHz}$   | —   | 0.6                | 1.0  | pF                |               |
|                                  | Response time                        | Rise time     | $t_r$  | $V_{CE}=2\text{V}, I_C=2\text{mA}, R_L=100\Omega$ | —                  | 4    | 18                | $\mu\text{s}$ |
|                                  |                                      | Fall time     | $t_f$  |   | —                  | 3    | 18                | $\mu\text{s}$ |
| *1 Common mode rejection voltage |                                      | CMR           | $T_a=25^\circ\text{C}, R_L=470\Omega, V_{CM}=1.5\text{kV (peak)}, I_F=0\text{mA}, V_{CC}=9\text{V}, V_{np}=100\text{mV}$ | 10  | —                  | —    | kV/ $\mu\text{s}$ |               |

\*1 Refer to Fig.1.

Fig.1 Test Circuit for Common Mode Rejection Voltage

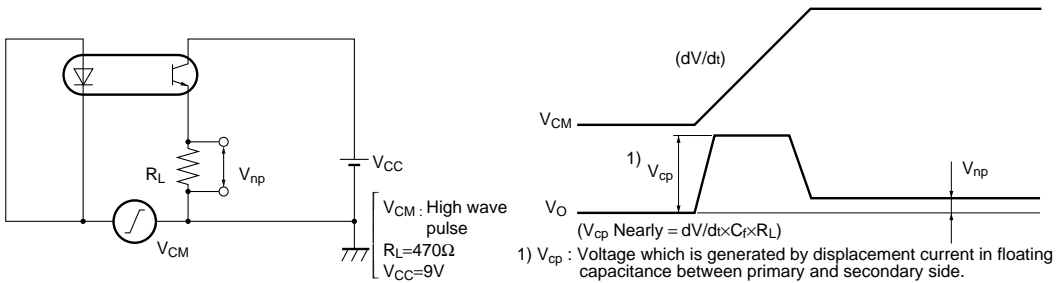


Fig.2 Forward Current vs. Ambient Temperature

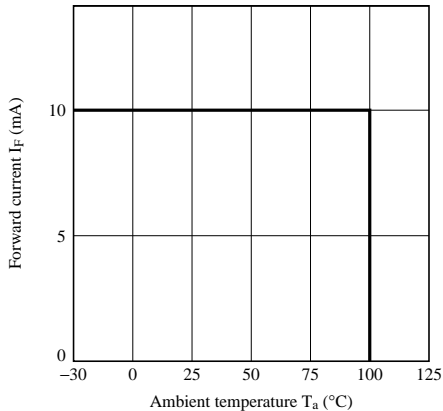
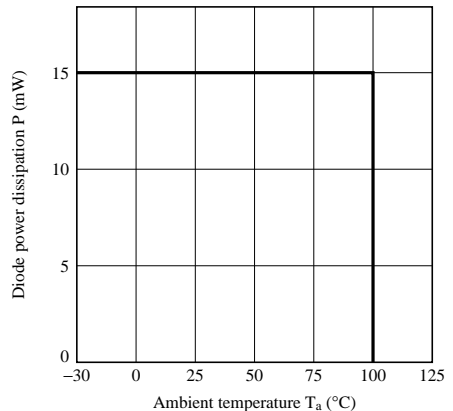
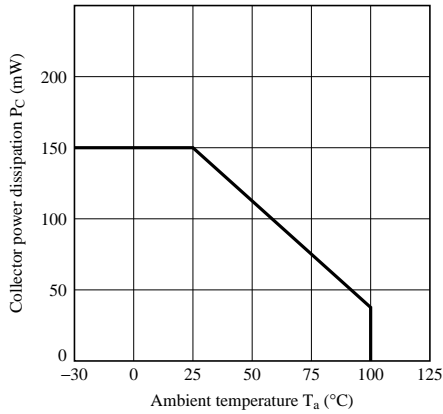


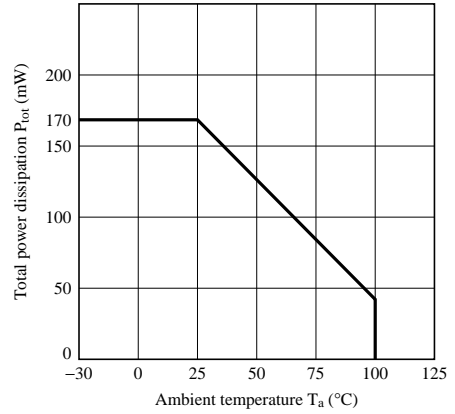
Fig.3 Diode Power Dissipation vs. Ambient Temperature



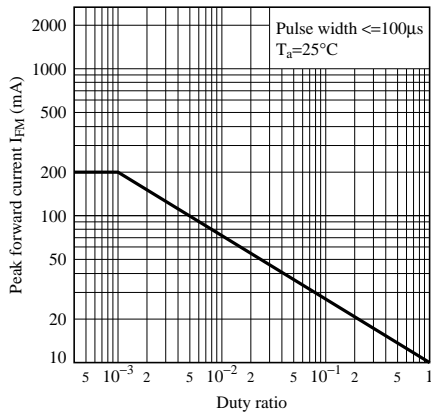
**Fig.4 Collector Power Dissipation vs. Ambient Temperature**



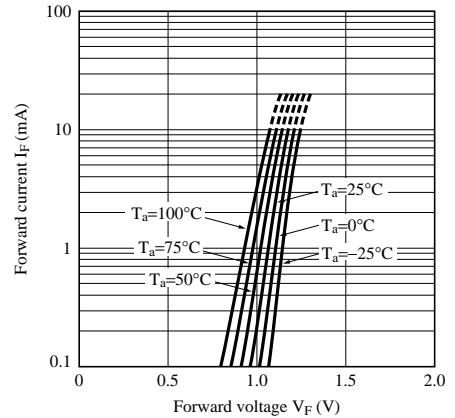
**Fig.5 Total Power Dissipation vs. Ambient Temperature**



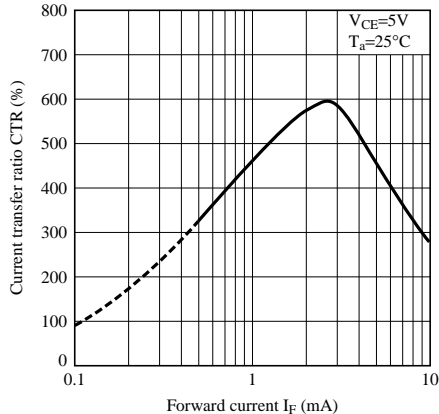
**Fig.6 Peak Forward Current vs. Duty Ratio**



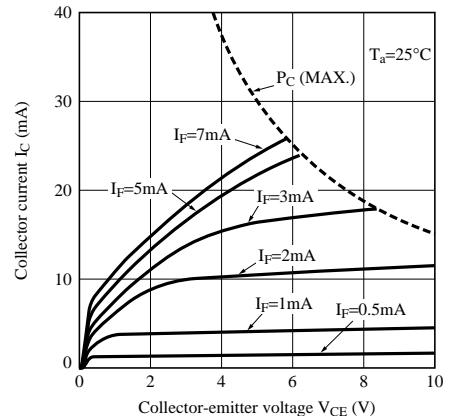
**Fig.7 Forward Current vs. Forward Voltage**



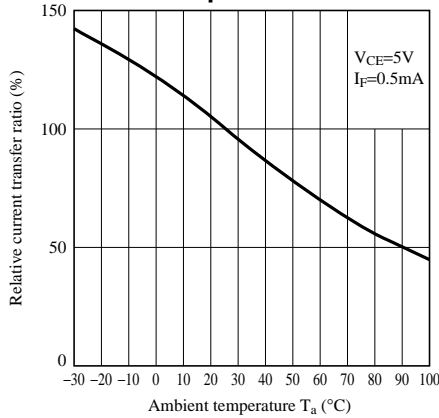
**Fig.8 Current Transfer Ratio vs. Forward Current**



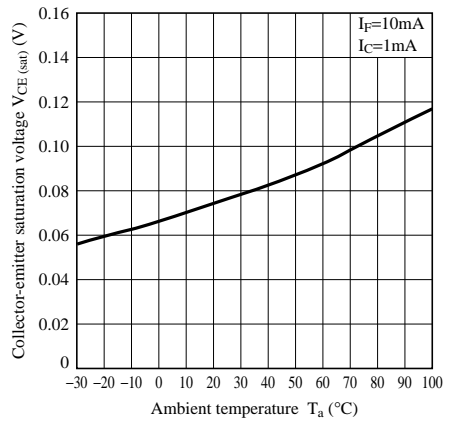
**Fig.9 Collector Current vs. Collector-emitter Voltage**



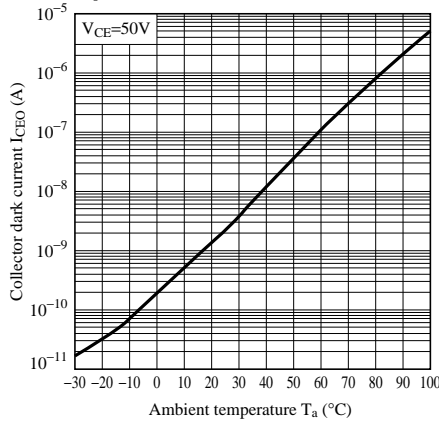
**Fig.10 Relative Current Transfer Ratio vs. Ambient Temperature**



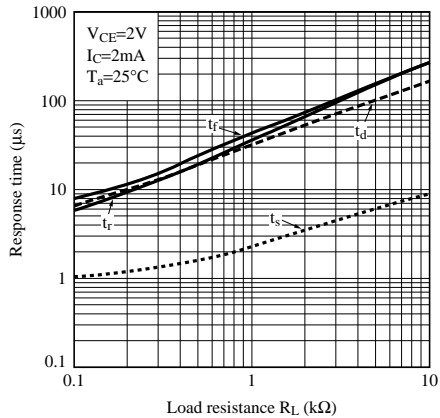
**Fig.11 Collector - emitter Saturation Voltage vs. Ambient Temperature**



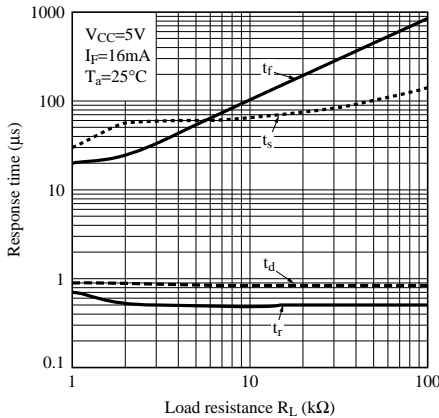
**Fig.12 Collector Dark Current vs. Ambient Temperature**



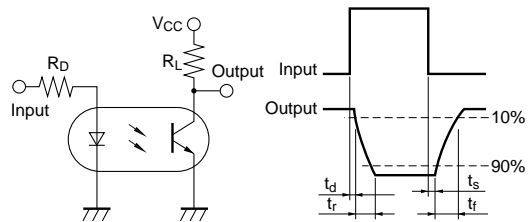
**Fig.13 Response Time vs. Load Resistance**



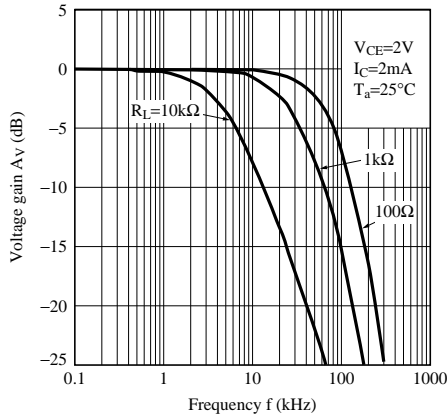
**Fig.14 Response Time vs. Load Resistance (Saturation)**



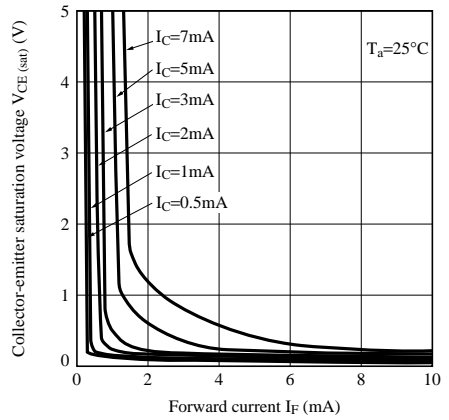
**Fig.15 Test Circuit for Response Time**



**Fig.16 Voltage Gain vs Frequency**

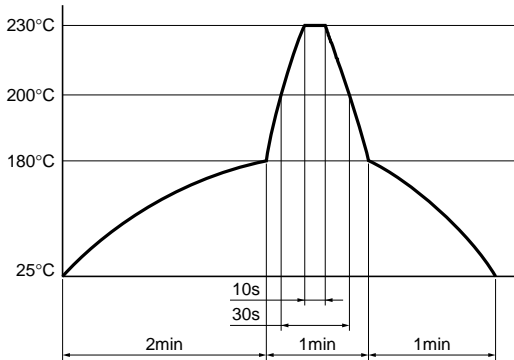


**Fig.17 Collector-emitter Saturation Voltage vs. Forward Current**



**Fig.18 Reflow Soldering**

Only one time soldering is recommended within the temperature profile shown below.



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